SC70 (E) Package Outline Drawing

NOTES:
1. PACKAGE BODY MATERIAL: LOW STRESS INJECTION MOLDED PLASTIC SILICA AND SILICON IMPREGNATED.
2. LEAD MATERIAL: COPPER ALLOY
3. LEAD PLATING: Sn/Pb SOLDER
4. DIMENSIONS ARE IN INCHES [MILLIMETERS]
5. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
6. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
7. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

<table>
<thead>
<tr>
<th>Part Number Suffix</th>
<th>Package Body Material</th>
<th>Lead Finish</th>
<th>MSL Rating</th>
<th>Package Marking[^3][^4]</th>
</tr>
</thead>
<tbody>
<tr>
<td>SC70</td>
<td>RoHS Compliant Mold Compound</td>
<td>Sn/Pb Solder</td>
<td>MSL1[^1]</td>
<td>NNN XXXX</td>
</tr>
<tr>
<td>SC70E</td>
<td>RoHS Compliant Mold Compound</td>
<td>100% matte Sn</td>
<td>MSL1[^2]</td>
<td>NNNE XXXX</td>
</tr>
</tbody>
</table>

[^1] Max peak reflow temperature of 235 °C
[^3] 4-Digit lot number XXXX
[^4] 3-Digit part number NNN
Suggested SC70 (E) PCB Land Pattern

NOTES:
1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.